Detail Study on Lattice Deformation and Recovery of GaN by Mg-ion-implantation and the Subsequent Thermal Annealing

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Application of ion-implantation technology to achieve p-type GaN remains a challenge. A significant obstacle is that the calculated anneal temperature (estimated around 1400-1500°C) is much higher than the growth temperature of GaN (around 1000°C). It is hard to recover the ion implantation damage and activate the implanted ions with GaN. After the Mg-ion-implantation, we confirmed change of lattice constant due to damage in the Mg implanted layer. To understand the implantation damage recovery, it is important to make a detailed study on lattice deformation and recovery of GaN by Mg ion implantation and the subsequent thermal annealing.

In this experiment, we grew u-GaN by MOVPE method and carried out the Mg-ion-implantation. We also carried out the thermal annealing at 1150° C. The X-ray $2\theta - \omega$ on (0002) face and (10-12) face results were plotted in fig.1. A strong sub-peak indicated the formation of the damaged layer showing the different lattice constant. After the post annealing, the sub-peak disappeared indicating the recovery from ion-implantation damage.

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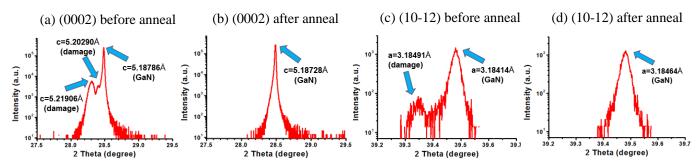


Fig. 1. XRD 2 θ - ω results on GaN after RT-single-implantation with PS-AlN¹.

1) Z. Sun, T. Nagayama, Y. Honda and H. Amano, "p-type GaN by Mg-ion Implantation with Pre-sputter Technique," ISPlasma 2014 / IC-PLANT 2014, no.06aC04OLN, Nagoya, Japan, Mar. 2014.